SDLS004 D2633, JANUARY 1981—REVISED MARCH 1988

- **Parallel Register Inputs ('LS592)**
- **Parallel 3-State I/O: Register Inputs/ Counter Outputs ('LS593)**
- **Counter has Direct Overriding Load and Clear**
- **Accurate Counter Frequency: DC to 20 MHz**

description

The 'LS592 comes in a 16-pin package and consists of a parallel input, 8-bit storage register feeding an 8-bit binary counter. Both the register and the counter have individual positive-edge-triggered clocks. In addition, the counter has direct load and clear functions. A low-going $\overline{RCO}$ pulse will be obtained when the counter reaches the hex word FF. Expansion is easily accomplished for two stages by connecting $\overline{RCO}$ of the first stage to $\overline{CCKEN}$ of the second stage. Cascading for larger count chains can be accomplished by connecting $\overline{RCO}$ of each stage to CCK of the following stage.

The 'LS593 comes in a 20-pin package and has all the features of the 'LS592 plus 3-state I/O, which provides parallel counter outputs. The tables below show the operation of the enable (CCKEN, $\overline{CCKEN}$) inputs. A register clock enable ($\overline{RCKEN}$) is also provided.

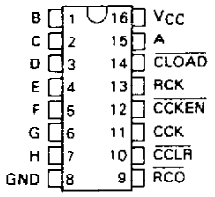
OUTPUT ENABLE CONTROL ('593 ONLY)

G	$\overline{G}$	A/Q_A thru H/Q_H
L	L	input mode
L	H	input mode
H	L	output mode
H	H	input mode

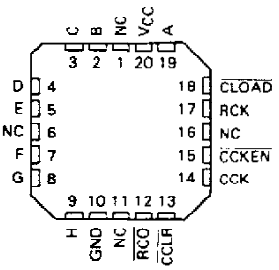
COUNTER CLOCK ENABLE CONTROL

CCKEN	$\overline{CCKEN}$	EFFECT ON CCK
L	L	Enable
L	H	Disable
H	L	Enable
H	H	Enable

SN54LS592 . . . J OR W PACKAGE
SN74LS592 . . . N PACKAGE
(TOP VIEW)

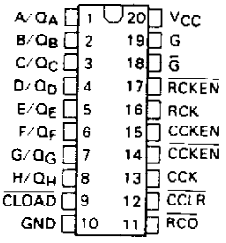


SN54LS592 . . . FK PACKAGE
(TOP VIEW)

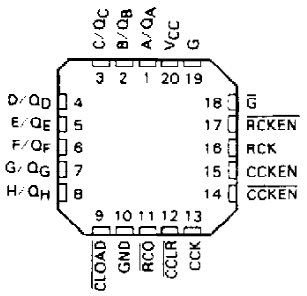


NC — No internal connection

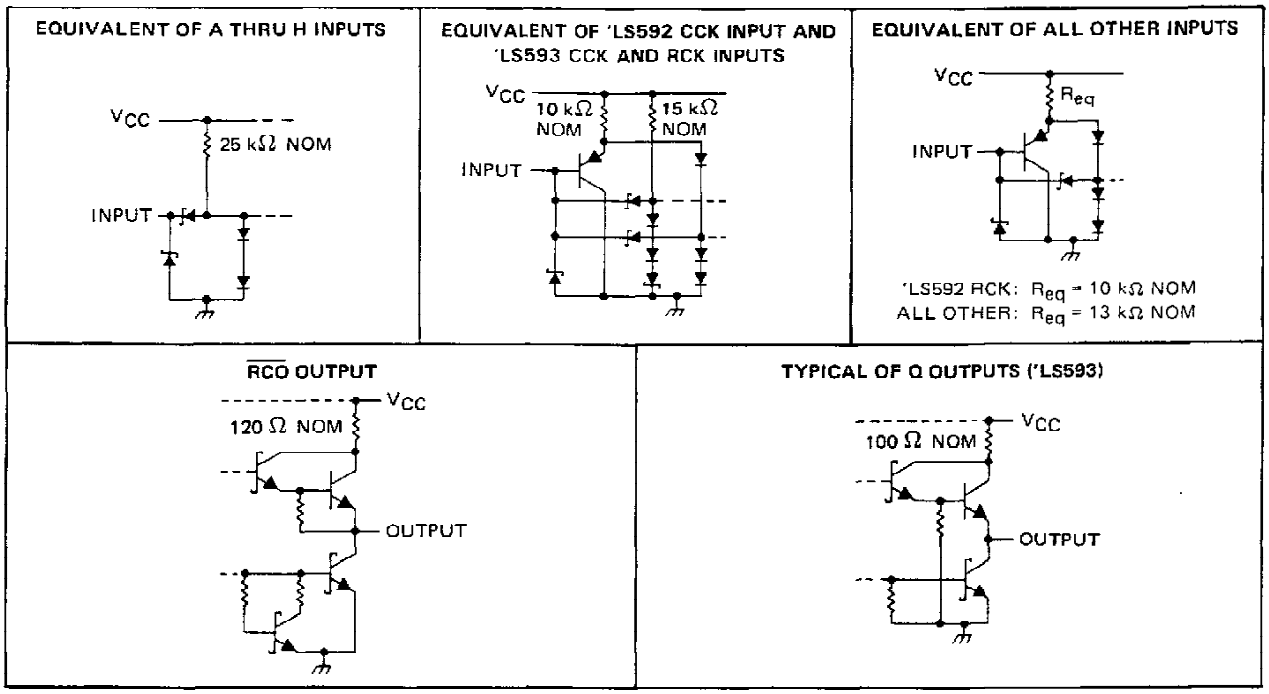
SN54LS593 . . . J OR W PACKAGE
SN74LS593 . . . DW OR N PACKAGE
(TOP VIEW)



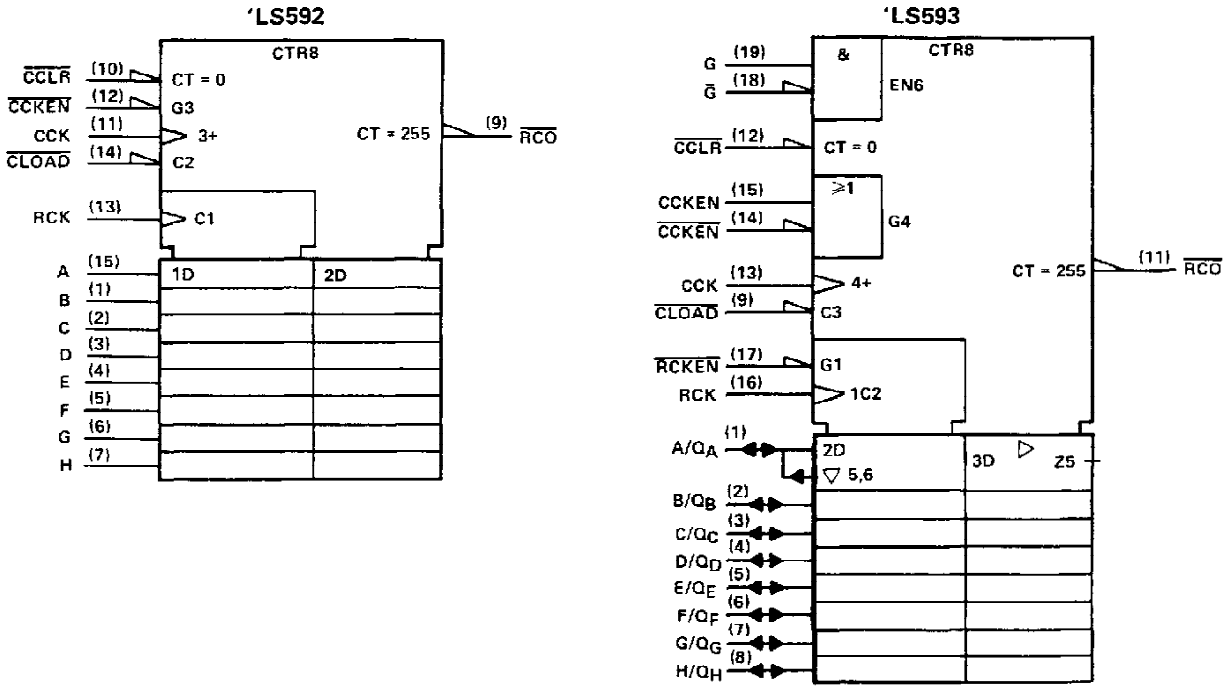
SN54LS593 . . . FK PACKAGE
(TOP VIEW)



schematics of inputs and outputs

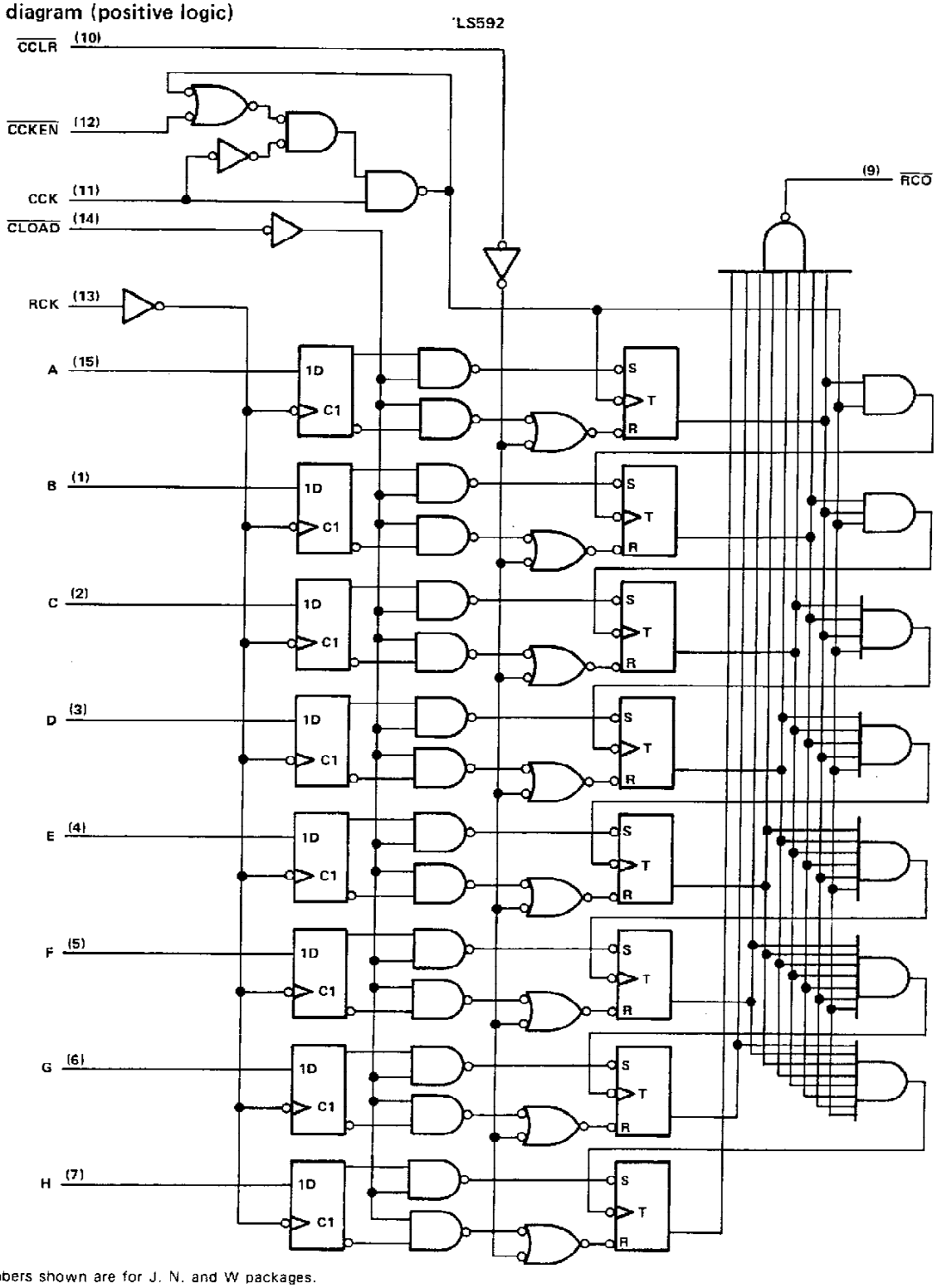


logic symbols†



†These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.
Pin numbers shown are for DW, J, N, and W packages.

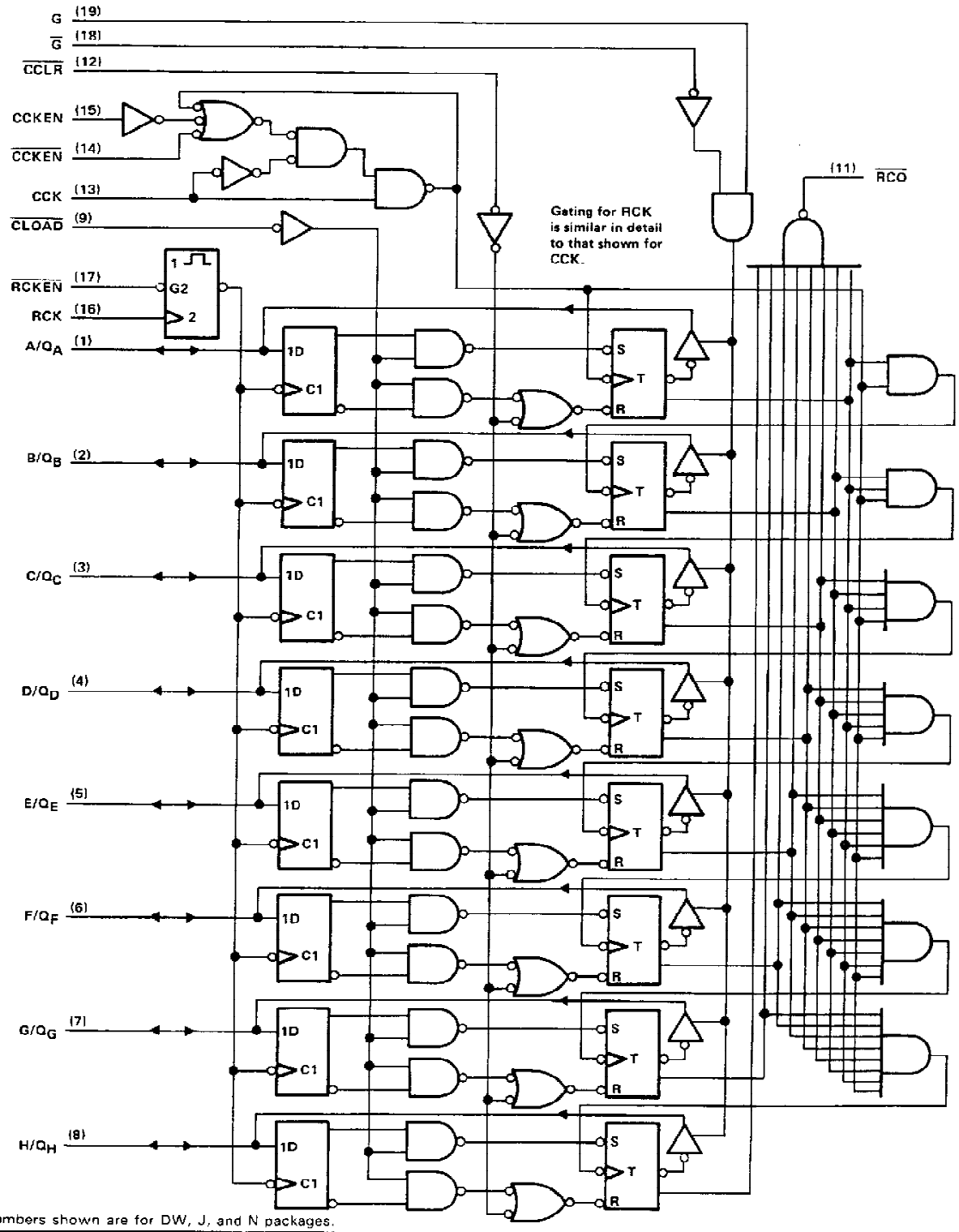
logic diagram (positive logic)



Pin numbers shown are for J, N, and W packages.

logic diagram (positive logic)

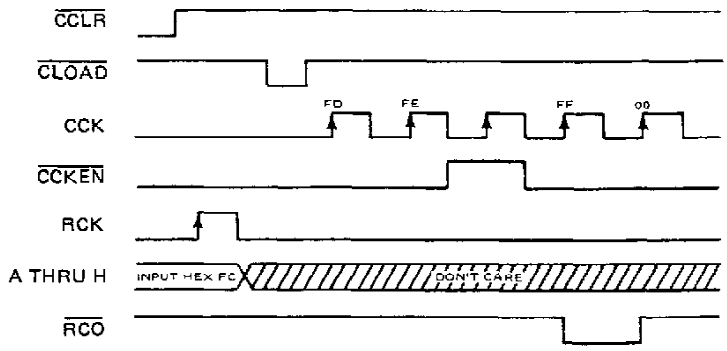
'LS593



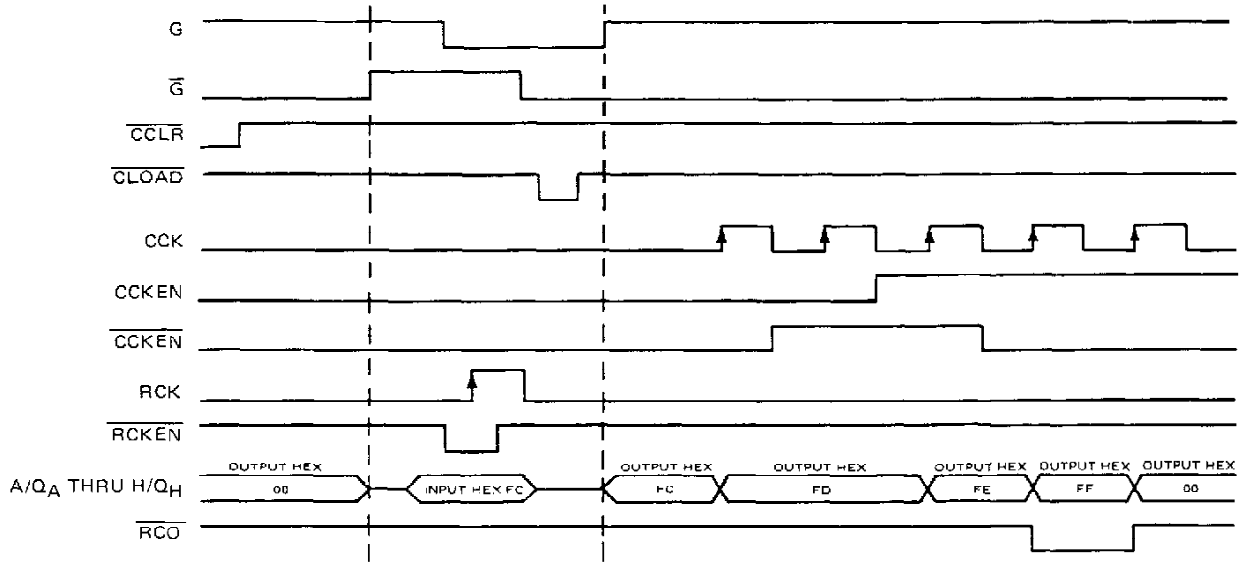
Pin numbers shown are for DW, J, and N packages.

typical operating sequences

'LS592



'LS593



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage (excluding I/O ports) . . . . . 7 V
Off-state output voltage (including I/O ports) . . . . . 5.5 V
Operating free-air temperature range: SN54LS592, SN54LS593 . . . . . −55°C to 125°C
SN74LS592, SN74LS593 . . . . . 0°C to 70°C
Storage temperature range . . . . . −65°C to 150°C

NOTE 1: Voltage values are with respect to the network ground terminal.

recommended operating conditions

			SN54LS'			SN74LS'			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage		4.5	5	5.5	4.75	5	5.25	V
V_{IH}	High-level input voltage		2			2			V
V_{IL}	Low-level input voltage				0.7			0.8	V
I_{OH}	High-level output current	$\overline{RCO}$			−1			−1	mA
		Q 'LS593 only			−1			−2.6	
I_{OL}	Low-level output current	$\overline{RCO}$			8			16	mA
		Q 'LS593 only			12			24	
f_{CCK}	Counter clock frequency		0		20	0		20	MHz
t_{w} (CCK)	Duration of counter clock pulse		25			25			ns
t_{w} ($\overline{CCLR}$)	Duration of counter clear pulse		20			20			ns
t_{w} (RCK)	Duration of register clock pulse		20			20			ns
t_{w} ($\overline{CLOAD}$)	Duration of counter load pulse		40			40			ns
t_{su}	Register enable setup time	$\overline{RCKEN}$ low to RCK ↑, 'LS593	20			20			ns
t_{su}	Counter enable setup time before CCK ↑	$\overline{CCKEN}$ low, 'LS592	30			30			ns
		$\overline{CCKEN}$ low or CCKEN high, 'LS593	30			30			
t_{su}	Setup time	$\overline{CCLR}$ inactive before CCK ↑	20			20			ns
		$\overline{CLOAD}$ inactive before CCK ↑	20			20			
		RCK ↑ before $\overline{CLOAD}$ ↑ (see Note 2)	30			30			
		Data A thru H before RCK ↑	20			20			
t_{h}	Hold time	Data A thru H after RCK ↑	0			0			ns
		All others	0			0			
T_{A}	Operating free-air temperature		−55		125	0		70	°C

NOTE 2: This time insures the data saved by RCK ↑ will also be loaded into the counter.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS†		SN54LS' MIN	SN54LS' TYP‡	SN54LS' MAX	SN74LS' MIN	SN74LS' TYP‡	SN74LS' MAX	UNIT
V_{IK}			V_{CC} = MIN, I_I = −18 mA				−1.5			−1.5	V
V_{OH}	'LS593 Q		V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = MAX	I_{OH} = −1 mA	2.4	3.2					V
				I_{OH} = −2.6 mA				2.4	3.1		
	$\overline{RCO}$			I_{OH} = −1 mA	2.4	3.2		2.4	3.2		
V_{OL}	'LS593 Q		V_{CC} = MIN, V_{IH} = 2 V, V_{IL} = MAX	I_{OL} = 12 mA		0.25	0.4		0.25	0.4	V
				I_{OL} = 24 mA					0.35	0.5	
	$\overline{RCO}$			I_{OL} = 8 mA		0.25	0.4		0.25	0.4	
				I_{OL} = 16 mA					0.35	0.5	
I_{OZH}	'LS593 Q		V_{CC} = MAX, V_{IH} = 2 V, V_{IL} = MAX, V_O = 2.7 V				20			20	μA
I_{OZL}	'LS593 Q		V_{CC} = MAX, V_{IH} = 2 V, V_{IL} = MAX, V_O = 0.4 V				−0.4			−0.4	mA
I_I	'LS593 Q		V_{CC} = MAX	V_I = 5.5 V			0.1			0.1	mA
	Others			V_I = 7 V			0.1			0.1	
I_{IH}			V_{CC} = MAX, V_I = 2.7 V				20			20	μA
I_{IL}	CCK		V_{CC} = MAX, V_I = 0.4 V				−0.8			−0.8	mA
	RCK	'LS592					−0.2			−0.2	
		'LS593					−0.8			−0.8	
	A thru H						−0.4			−0.4	
	Others						−0.2			−0.2	
I_{OS}§	'LS593 Q		V_{CC} = MAX, V_O = 0 V		−30		−130	−30		−130	mA
	$\overline{RCO}$				−20		−100	−20		−100	
I_{CC}	'LS592	I_{CCH}	V_{CC} = MAX, All possible inputs grounded, All outputs open			40	60		40	60	mA
		I_{CCL}				40	60		40	60	
	'LS593	I_{CCH}				47	70		47	70	
		I_{CCL}				53	80		53	80	
		I_{CCZ}				57	85		57	85	

†For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.
‡All typical values are at V_{CC} = 5 V, T_A = 25°C.
§Not more than one output should be shorted at a time and the duration of the short-circuit should not exceed one second.

switching characteristics, V_{CC} = 5 V, T_A = 25°C, (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	'LS592			'LS593			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
f_{max}	CCK	$\overline{RCO}$	R_L = 1 kΩ, C_L = 30 pF	20	35		20	35		MHz
t_{PLH}	CCK ↑	Q	R_L = 667 Ω, C_L = 45 pF					14	21	ns
t_{PHL}	CCK ↑	Q						26	39	ns
t_{PLH}	$\overline{CLOAD}$ ↓	Q						34	51	ns
t_{PHL}	$\overline{CLOAD}$ ↓	Q						28	42	ns
t_{PHL}	$\overline{CCLR}$ ↓	Q						25	38	ns
t_{PZH}	G ↑	Q						31	47	ns
t_{PZL}	G ↑	Q						27	40	ns
t_{PZH}	$\overline{G}$ ↓	Q						29	45	ns
t_{PZL}	$\overline{G}$ ↓	Q						31	47	ns
t_{PHZ}	G ↓	Q	R_L = 667 Ω, C_L = 5 pF					33	50	ns
t_{PLZ}	G ↓	Q						35	52	ns
t_{PHZ}	$\overline{G}$ ↑	Q						26	39	ns
t_{PLZ}	$\overline{G}$ ↑	Q						28	42	ns
t_{PLH}	CCK ↑	$\overline{RCO}$	R_L = 1 kΩ, C_L = 30 pF		15	23		14	21	ns
t_{PHL}	CCK ↑	$\overline{RCO}$			20	30		20	30	ns
t_{PLH}	$\overline{CLOAD}$ ↓	$\overline{RCO}$			31	47		31	47	ns
t_{PHL}	$\overline{CLOAD}$ ↓	$\overline{RCO}$			27	41		27	41	ns
t_{PLH}	$\overline{CCLR}$ ↓	$\overline{RCO}$			30	45		30	45	ns
t_{PLH}	RCK ↑	$\overline{RCO}$	R_L = 1 kΩ; C_L = 30 pF $\overline{CLOAD}$ = L		35	53		42	63	ns
t_{PHL}	RCK ↑	$\overline{RCO}$			30	45		33	50	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
5962-87621012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-8762101EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
5962-8762101EA	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
5962-8762101FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
5962-8762101FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SN54LS592J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SN54LS592J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SN54LS593J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type
SN54LS593J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type
SN74LS592D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS592D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS592DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS592DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS592DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS592DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS592DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS592DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS592DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS592DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS592DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS592DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS592N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS592N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS592N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS592N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS592NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS592NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS592NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS592NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
SN74LS592NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS592NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS592NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS592NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS593N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS593N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI
SN74LS593N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI
SN74LS593NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS593NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SNJ54LS592FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS592FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS592J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS592J	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS592W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS592W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS593FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS593FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
SNJ54LS593J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type
SNJ54LS593J	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type
SNJ54LS593W	OBSOLETE			20		TBD	Call TI	Call TI
SNJ54LS593W	OBSOLETE			20		TBD	Call TI	Call TI

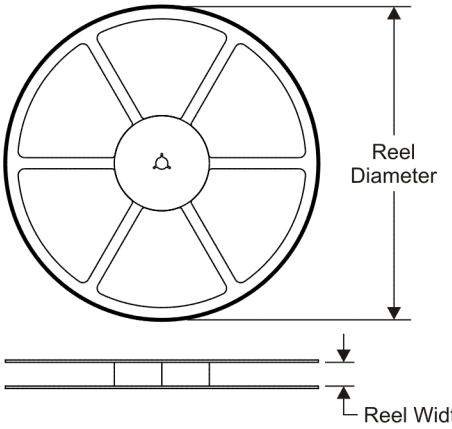
(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

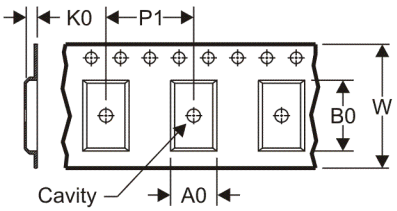
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

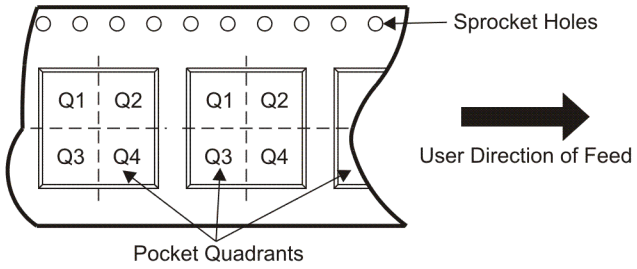


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

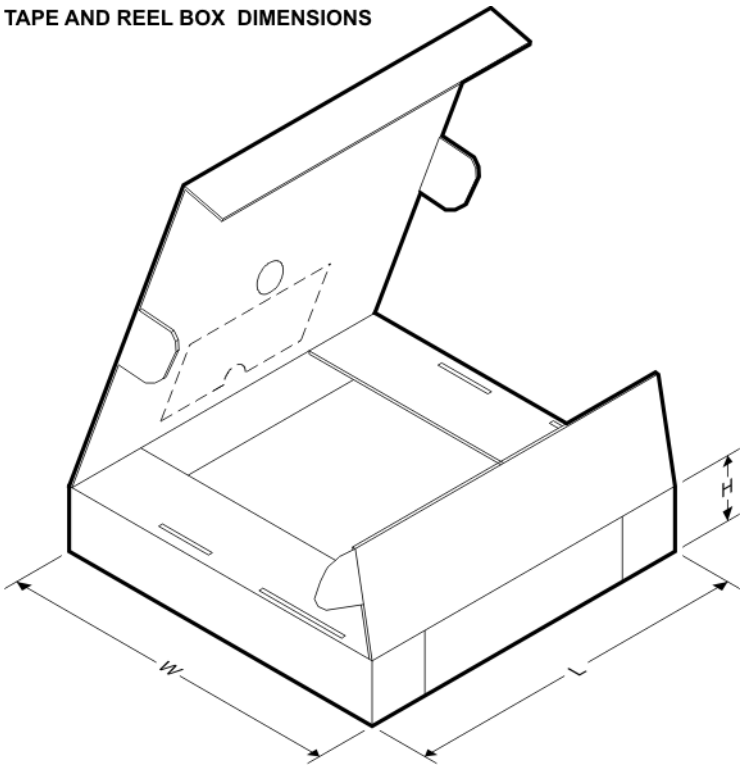
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LS592DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74LS592NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74LS593DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS



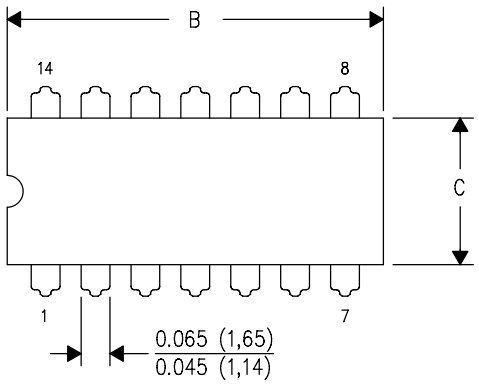
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LS592DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74LS592NSR	SO	NS	16	2000	346.0	346.0	33.0
SN74LS593DWR	SOIC	DW	20	2000	346.0	346.0	41.0

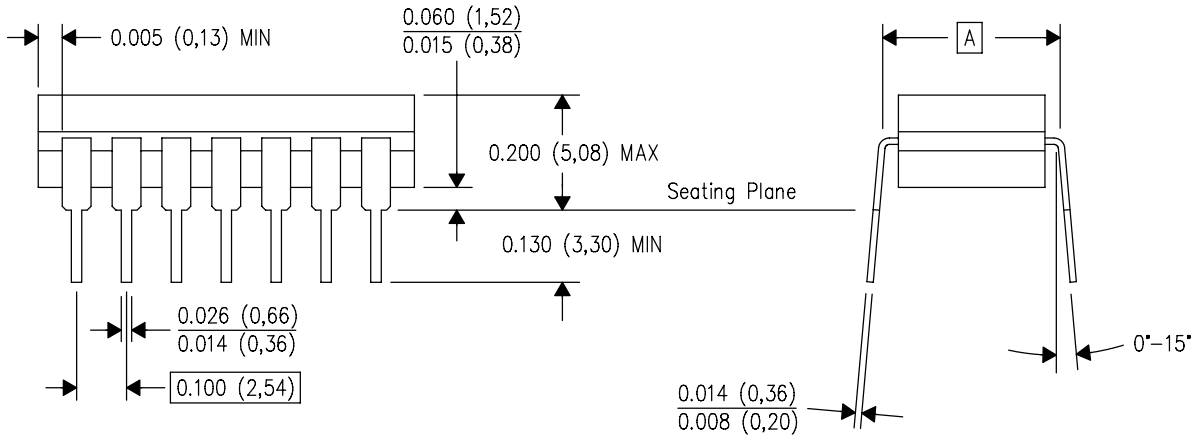
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



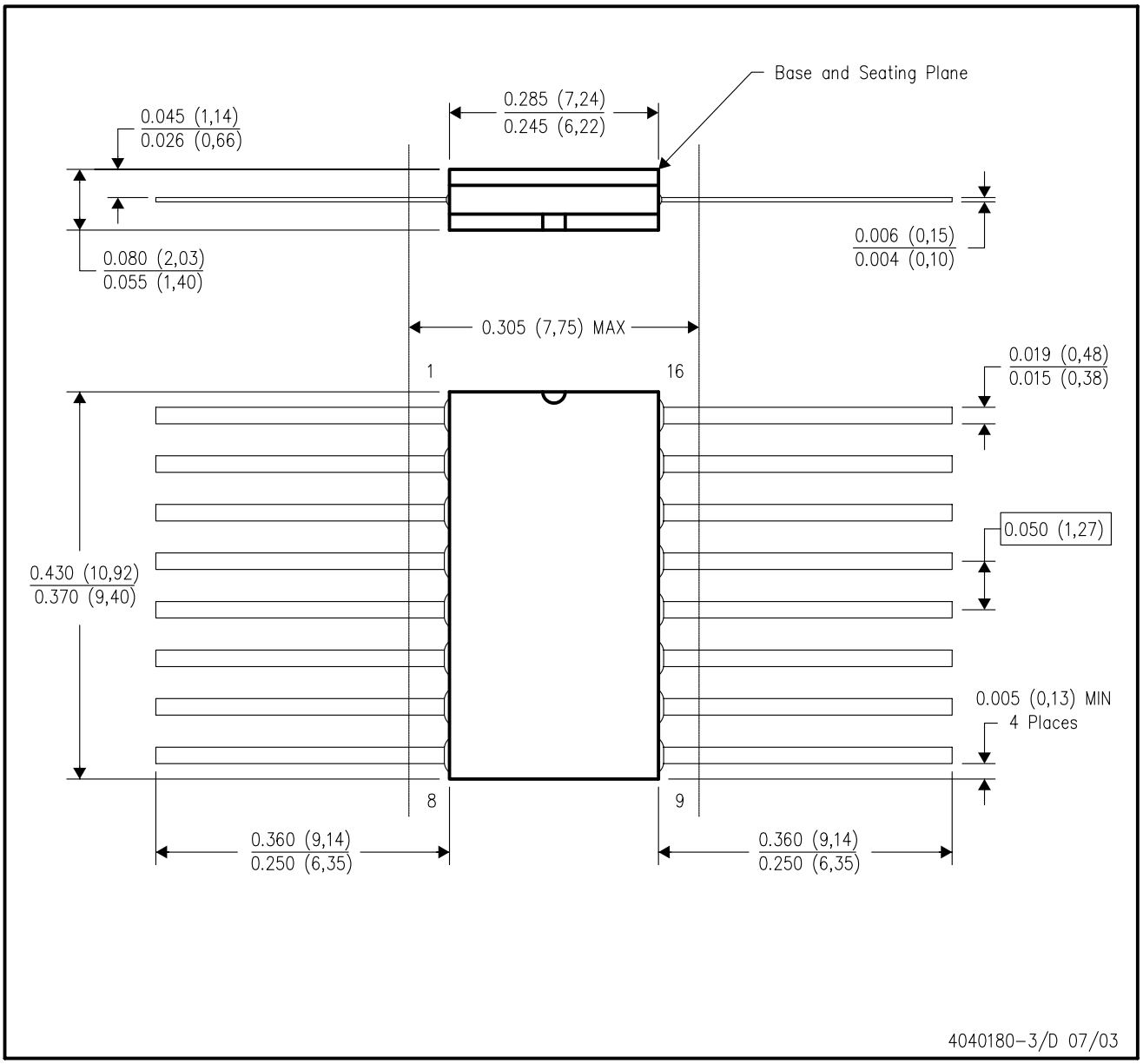
DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

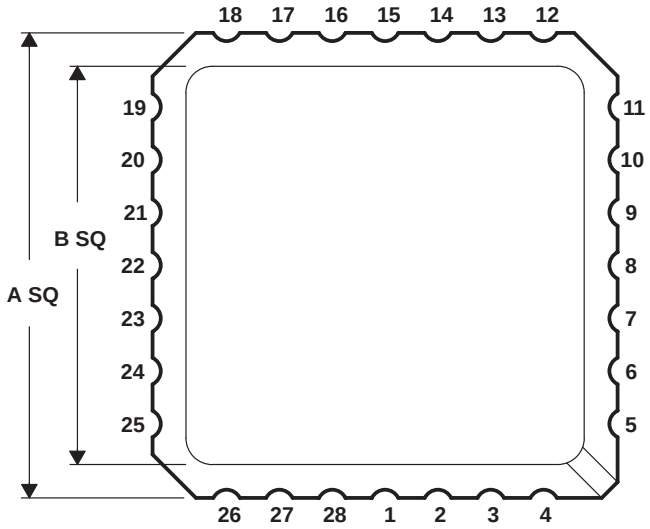
W (R–GDFP–F16) CERAMIC DUAL FLATPACK



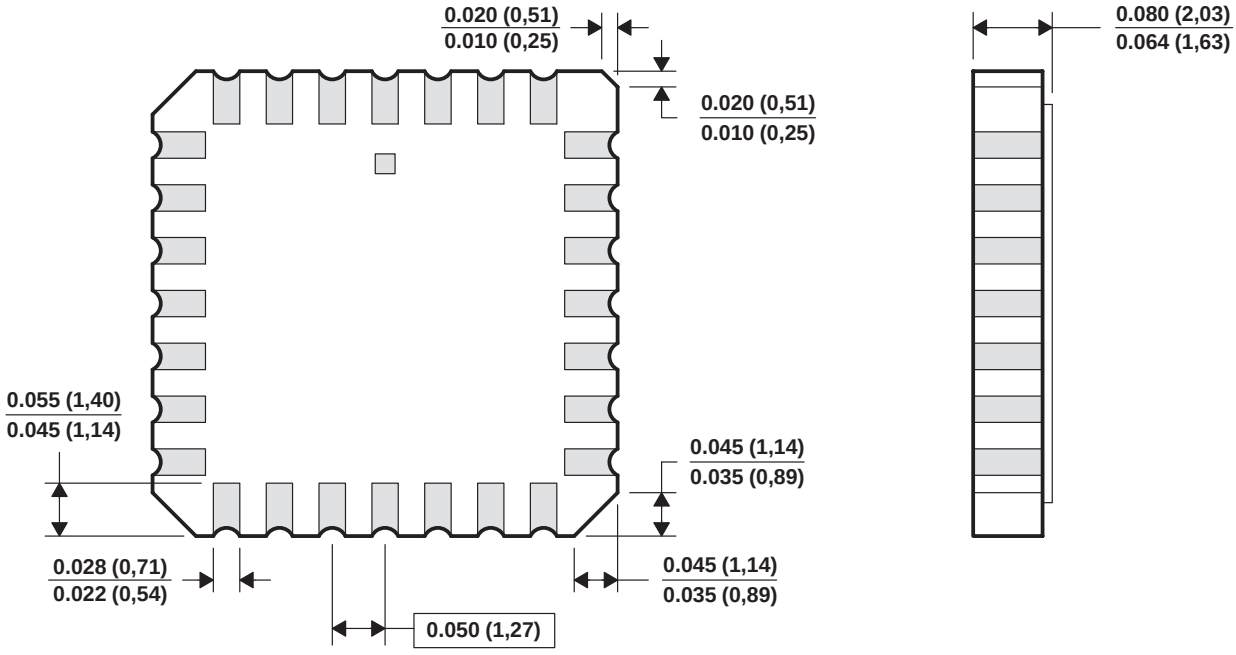
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP1–F16 and JEDEC MO–092AC

FK (S-CQCC-N)** **LEADLESS CERAMIC CHIP CARRIER**

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.739 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



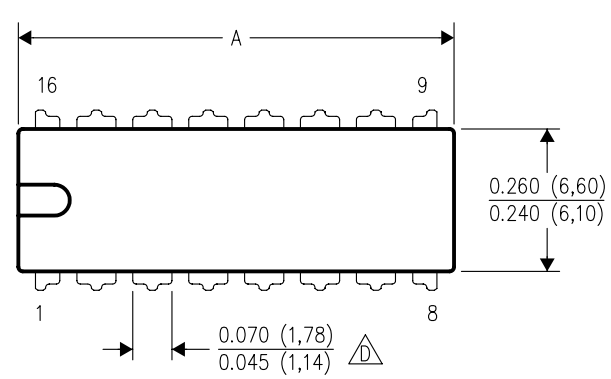
4040140/D 10/96

NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. The terminals are gold plated.
E. Falls within JEDEC MS-004

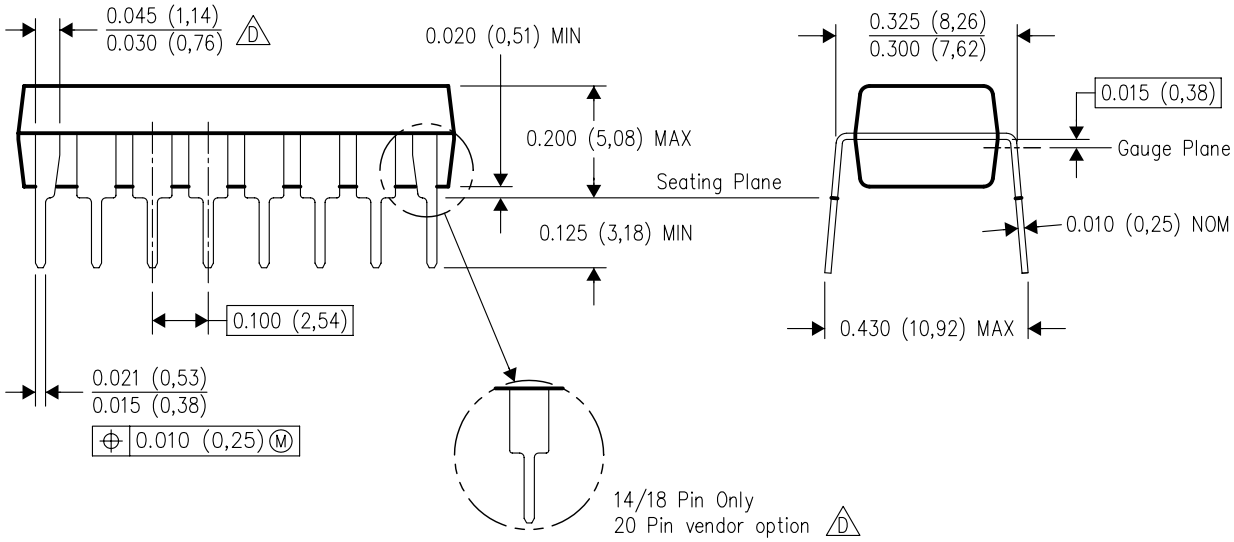
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



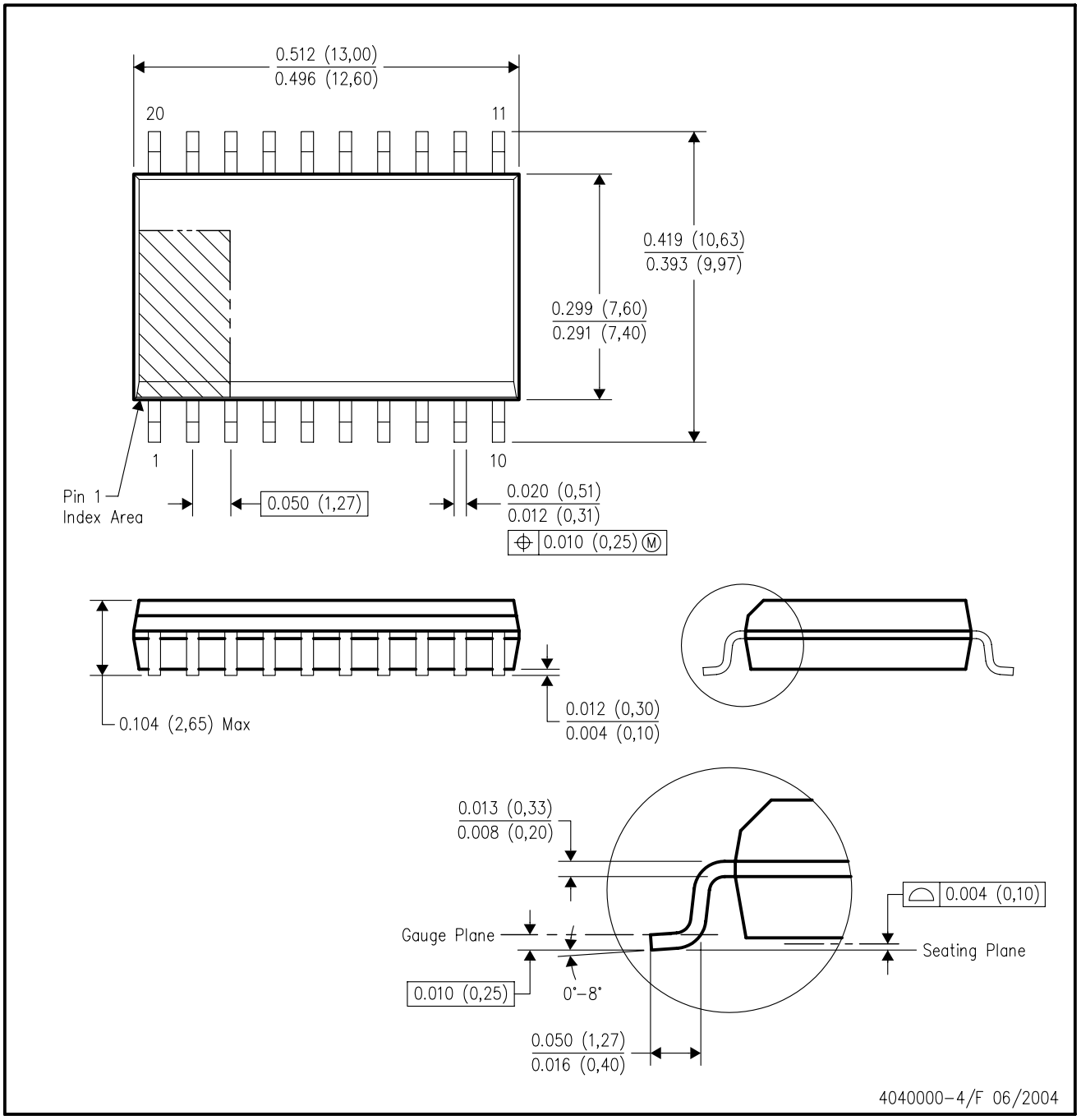
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

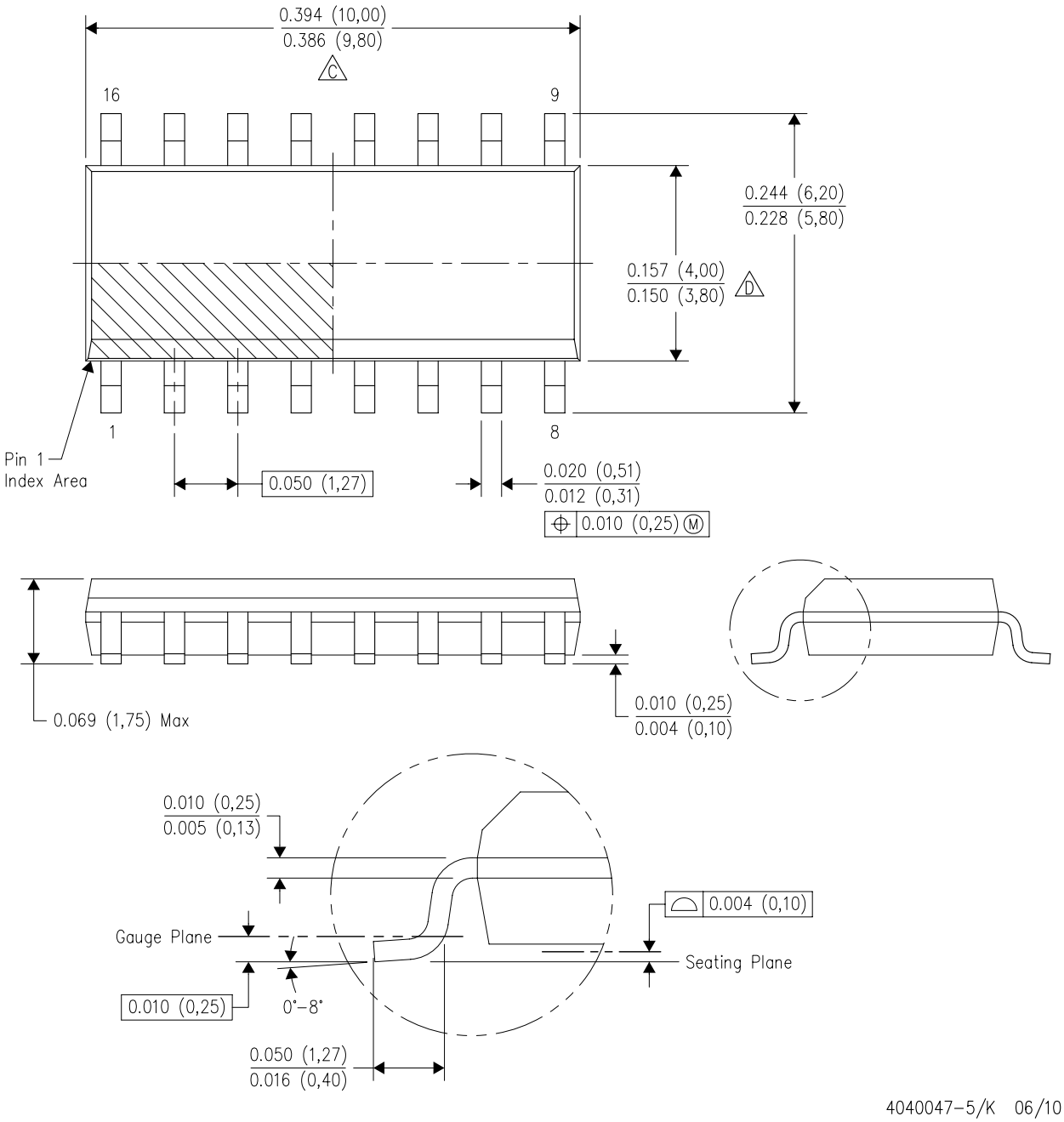
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R–PDSO–G20) PLASTIC SMALL–OUTLINE PACKAGE



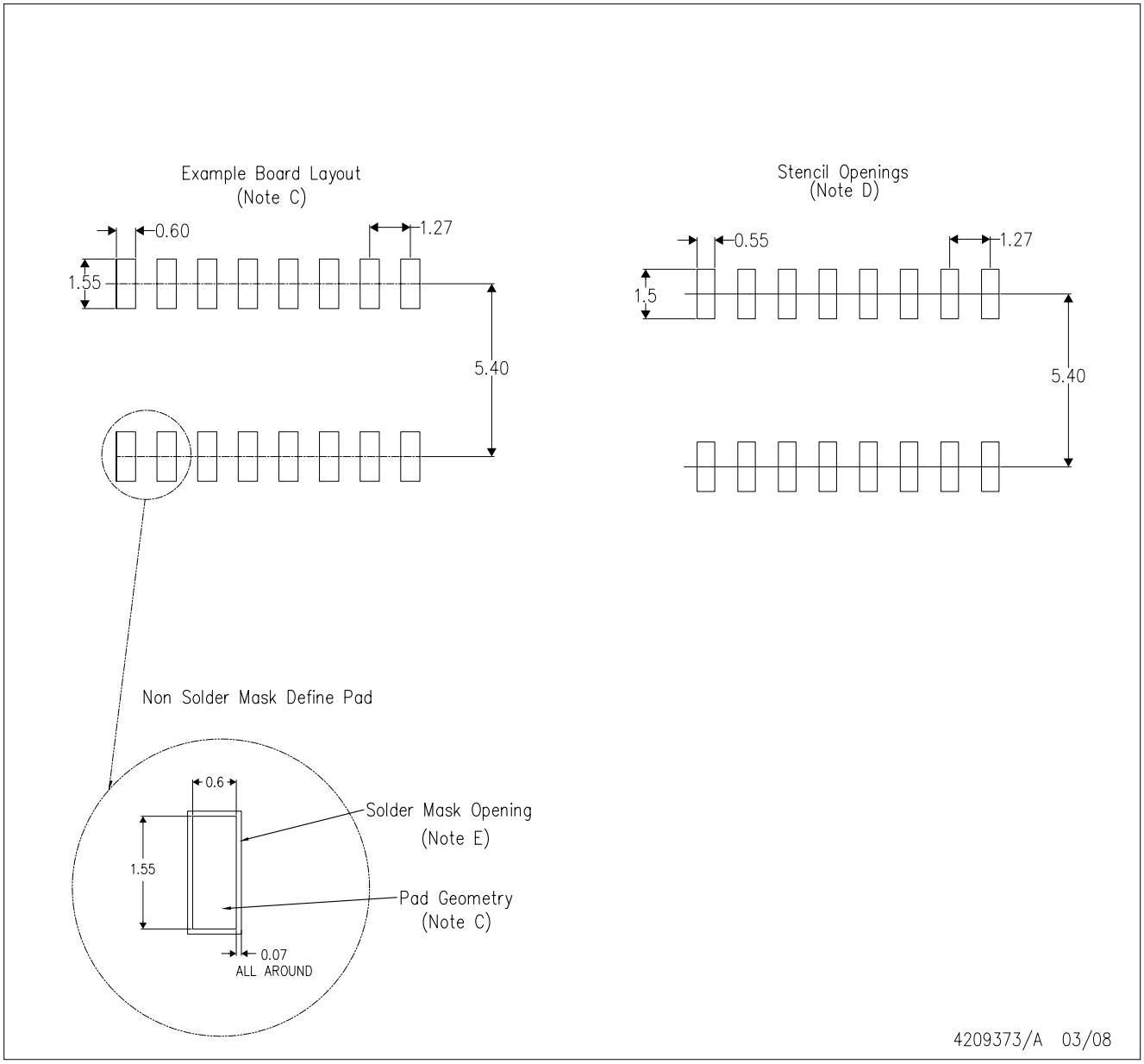
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–013 variation AC.

D (R–PDSO–G16) PLASTIC SMALL–OUTLINE PACKAGE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
E. Reference JEDEC MS–012 variation AC.

D(R–PDSO–G16)

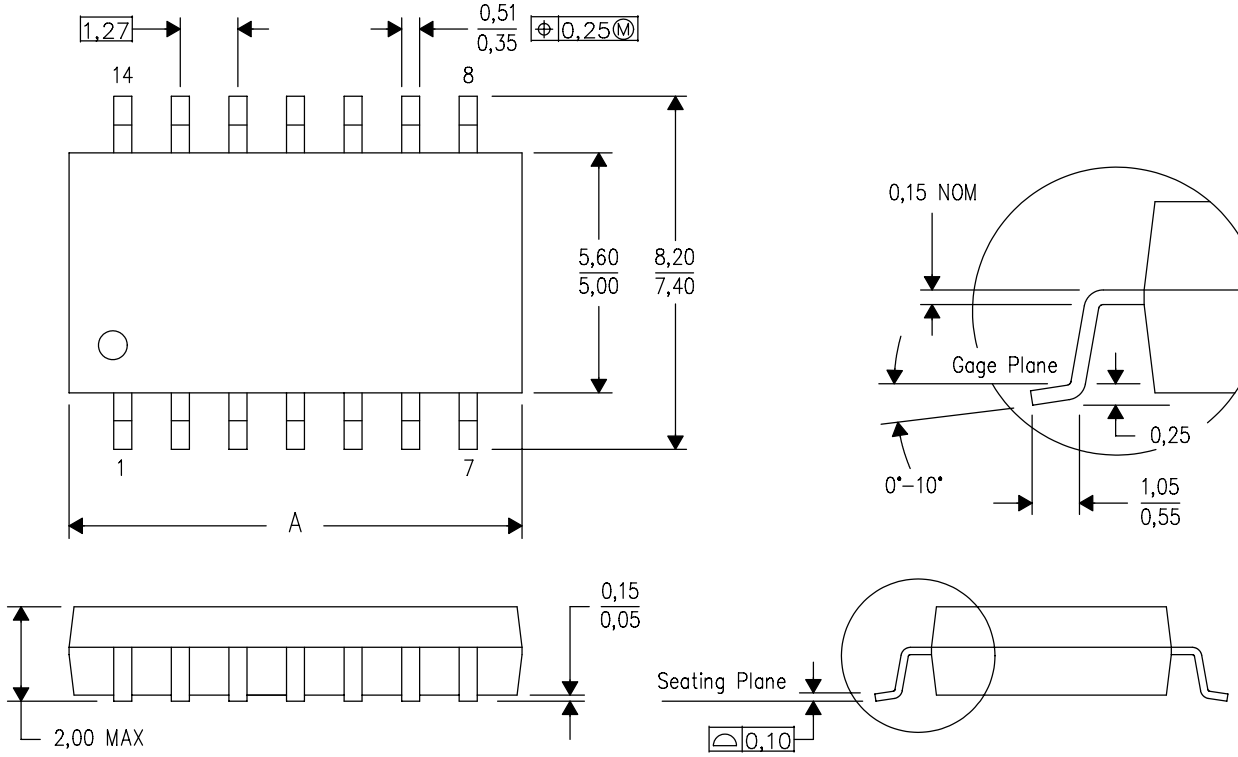


NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Refer to IPC7351 for alternate board design.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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